METHOD OF FORMING BALL GRID ARRAY CONTACTS

ABSTRACT

The invention is to a method for forming solder contact balls for a ball grid array semiconductor package by aligning a sheet of solder (18) on a semiconductor package substrate (15) having a plurality of contact areas (16). A heated wire grid (20,21)is applied to the sheet of solder (18) to separate the solder sheet into a plurality of individual solder plates (22), one each for each contact area (16). Heat is then applied to the solder plates (22) and substrate (15) to melt the solder plates (22) and to reflow the melted solder to form a solder ball (23) at each contact area (16).

Figure 2